

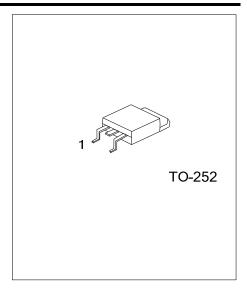
UNISONIC TECHNOLOGIES CO., LTD

F2N60 **Power MOSFET**

2A, 600V N-CHANNEL **POWER MOSFET**

DESCRIPTION

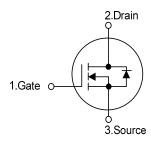
The UTC F2N60 is a high voltage power MOSFET and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and have a high rugged avalanche characteristics. This power MOSFET is usually used at high speed switching applications in power supplies, PWM motor controls, high efficient DC to DC converters and bridge circuits.



FEATURES

- * $R_{DS(ON)} = 5\Omega@V_{GS} = 10V$
- * Ultra Low gate charge (typical 16nC)
- * Fast switching capability
- * Avalanche energy specified
- * Improved dv/dt capability, high ruggedness

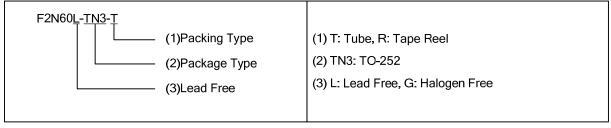
SYMBOL



ORDERING INFORMATION

Ordering Number		Daalaaaa	Pin Assignment			Da alain a	
Lead Free	Halogen Free	Package	1	2	3	Packing	
F2N60L-TN3-T	F2N60G-TN3-T	TO-252	G	D	S	Tube	
F2N60L-TN3-R	F2N60G-TN3-R	TO-252	G	D	S	Tape Reel	

Note: Pin Assignment: G: Gate D: Drain S: Source



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■ **ABSOLUTE MAXIMUM RATINGS** (T_C=25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT	
Drain-Source Voltage		V_{DSS}	600	V	
Gate-Source Voltage		V_{GSS}	±30	V	
Avalanche Current (Note 2)		I _{AR}	2.0	Α	
D. i. O	Continuous	I _D	2.0	Α	
Drain Current	Pulsed (Note 2)	I _{DM}	8.0	Α	
A	Single Pulsed (Note 3)	E _{AS}	100	mJ	
Avalanche Energy	Repetitive (Note 2)	E _{AR}	4.5	mJ	
Peak Diode Recovery dv.	ak Diode Recovery dv/dt (Note 4)		4.5	V/ns	
Power Dissipation (T _C = 2	ower Dissipation (T _C = 25°C)		44	W	
Junction Temperature		Τ _J	+150	°C	
Operating Temperature		T _{OPR}	-55 ~ +150	°C	
Storage Temperature		T _{STG}	-55 ~ +150	°C	

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

- 2. Repetitive Rating : Pulse width limited by T_{J}
- 3. L=64mH, I_{AS} =2.0A, V_{DD} =50V, R_{G} =25 Ω , Starting T_{J} = 25°C
- 4. $I_{SD} \le 2.4A$, di/dt $\le 200A/\mu s$, $V_{DD} \le BV_{DSS}$, Starting $T_J = 25^{\circ}C$

■ THERMAL DATA

PARAMETER	SYMBOL	RATINGS	UNIT	
Junction to Ambient	θ_{JA}	100	°C/W	
Junction to Case	θ_{Jc}	2.87	°C/W	

F2N60 Power MOSFET

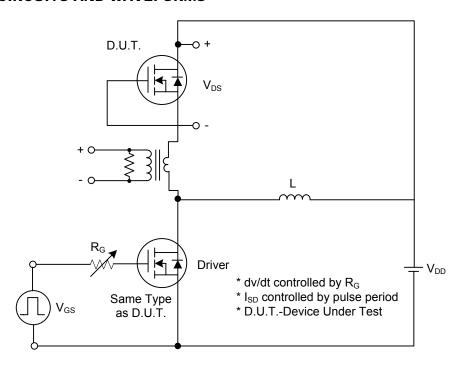
■ ELECTRICAL CHARACTERISTICS (T_J =25°C, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT		
OFF CHARACTERISTICS								
Drain-Source Breakdown Voltage	BV _{DSS}	$V_{GS} = 0V, I_D = 250\mu A$	600			V		
Drain-Source Leakage Current	I _{DSS}	$V_{DS} = 600V, V_{GS} = 0V$			10	μΑ		
Forward	locc l	$V_{GS} = 30V, V_{DS} = 0V$			100	nA		
Gate-Source Leakage Current Reverse		$V_{GS} = -30V, V_{DS} = 0V$			-100	nA		
Breakdown Voltage Temperature Coefficient	$\triangle BV_{DSS}/\triangle T_{J}$	I _D =250μA, Referenced to 25°C		0.4		V/°C		
ON CHARACTERISTICS								
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.0		40	V		
Static Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} = 10V, I _D =1A		4.7	5	Ω		
DYNAMIC CHARACTERISTICS								
Input Capacitance	C _{ISS}	05)/)/ 0)/			350	pF		
Output Capacitance	Coss	V _{DS} =25V, V _{GS} =0V, If =1MHz			50	pF		
Reverse Transfer Capacitance	C _{RSS}	I = IIVIHZ			7	pF		
SWITCHING CHARACTERISTICS								
Turn-On Delay Time	t _{D (ON)}			35	40	ns		
Turn-On Rise Time	t _R	V _{DD} =300V, I _D =2.4A,		50	60	ns		
Turn-Off Delay Time	t _{D(OFF)}	R _G =25Ω (Note 1, 2)		85	100	ns		
Turn-Off Fall Time	t _F			70	80	ns		
Total Gate Charge	Q_G	1001/11/1001/		16	20	nC		
Gate-Source Charge	Q_{GS}	V _{DS} =480V, V _{GS} =10V,		3.8		nC		
Gate-Drain Charge	Q_{GD}	I _D =2.4A (Note 1, 2)		4.6		nC		
DRAIN-SOURCE DIODE CHARACTERISTIC	cs			ā.				
Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS} = 0 \text{ V}, I_{SD} = 2.0 \text{ A}$			1.4	V		
Continuous Drain-Source Current	I _{SD}				2.0	Α		
Pulsed Drain-Source Current	I _{SM}				8.0	Α		
Reverse Recovery Time	t _{rr}	V _{GS} = 0 V, I _{SD} = 2.4A,	90	100	130	ns		
Reverse Recovery Charge	Q_{RR}	di/dt = 100 A/µs (Note 1)		0.72		μC		

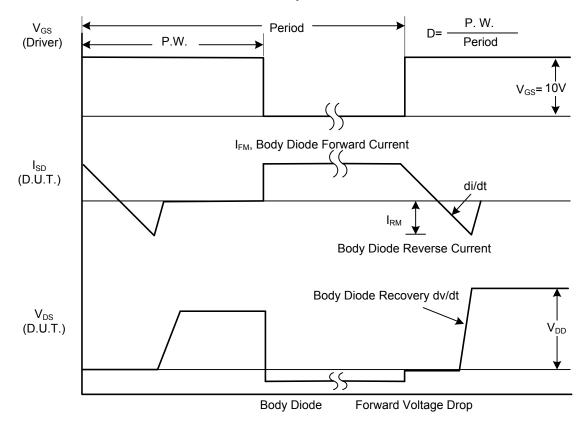
Notes: 1. Pulse Test: Pulse width ≤ 300µs, Duty cycle≤2%

^{2.} Essentially independent of operating temperature

■ TEST CIRCUITS AND WAVEFORMS



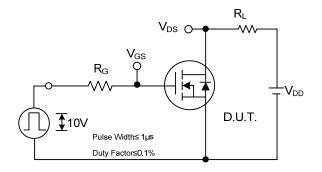
Peak Diode Recovery dv/dt Test Circuit

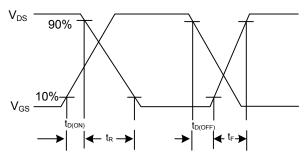


Peak Diode Recovery dv/dt Waveforms

F2N60

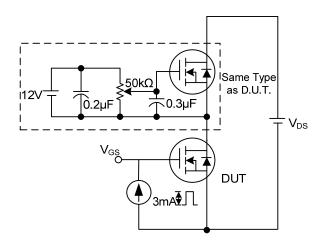
■ TEST CIRCUITS AND WAVEFORMS (Cont.)

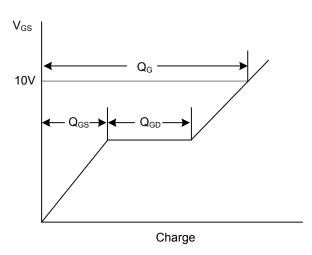




Switching Test Circuit

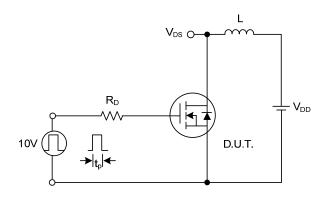
Switching Waveforms

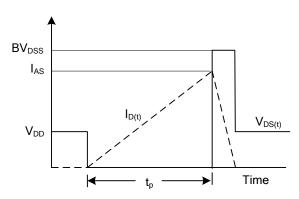




Gate Charge Test Circuit

Gate Charge Waveform

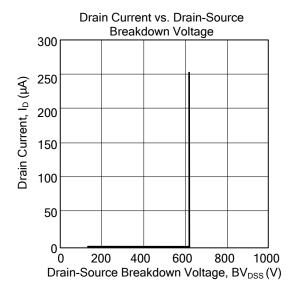


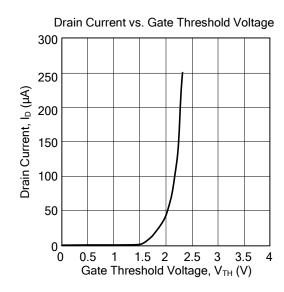


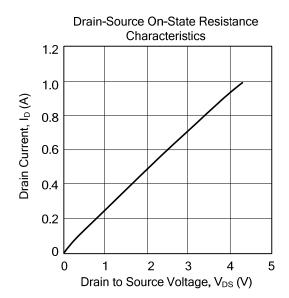
Unclamped Inductive Switching Test Circuit

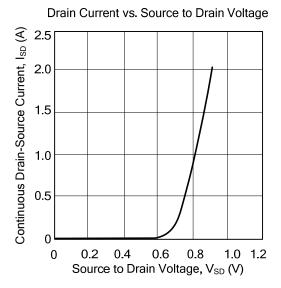
Unclamped Inductive Switching Waveforms

■ TYPICAL CHARACTERISTICS









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